

## ABSTRACT OF THE DISCLOSURE

An insulating substrate (17) includes a surface  
conductive layer (25) fixedly laminated on a surface of the  
plate-like semiconductor body (21) via a surface side  
fixing member (24, 26). The surface side fixing member (24,  
5 26) includes a first fixing portion (26) for fixing one  
part (25a) of the surface conductive layer (25) located  
underneath the joint portion (15) of the electrode terminal  
(14), and a second fixing portion (24) for fixing the other  
10 part (25b) of the surface conductive layer (25) which is  
not located underneath the joint portion (15), and a fixing  
strength exhibited by the first fixing portion (26) is  
smaller than that exhibited by the second fixing portion  
(24).